

MA2SP050G

Silicon epitaxial planar type

For high frequency attenuator

■ Features

- High performance forward current I_F controlled forward dynamic resistance r_f
- Small terminal capacitance C_t
- Miniature package and surface mounting type

■ Package

- Code
SSMini2-F4
- Pin Name
1: Anode
2: Cathode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

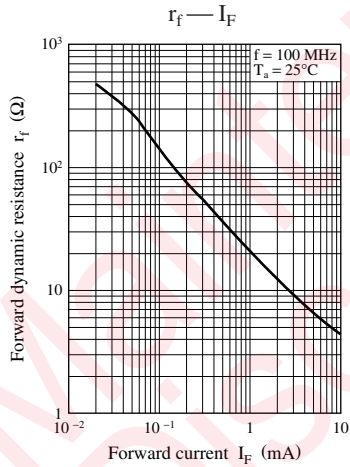
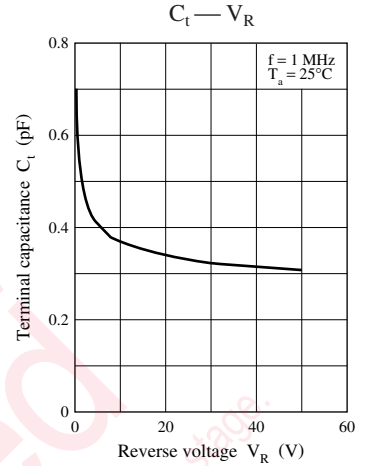
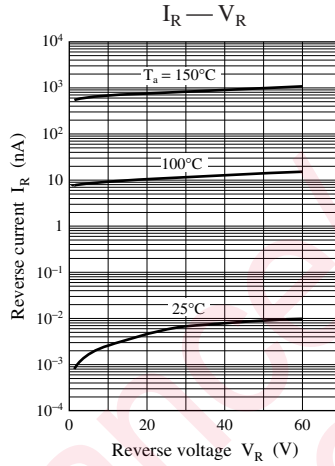
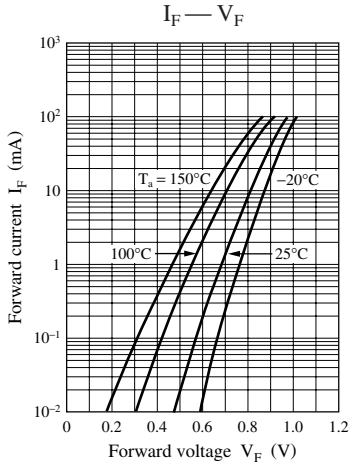
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	50	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Marking Symbol: 6P

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	I_R	$V_R = 60 \text{ V}$			100	nA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			2.4	pF
Forward dynamic resistance	r_f	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$			5.5	Ω

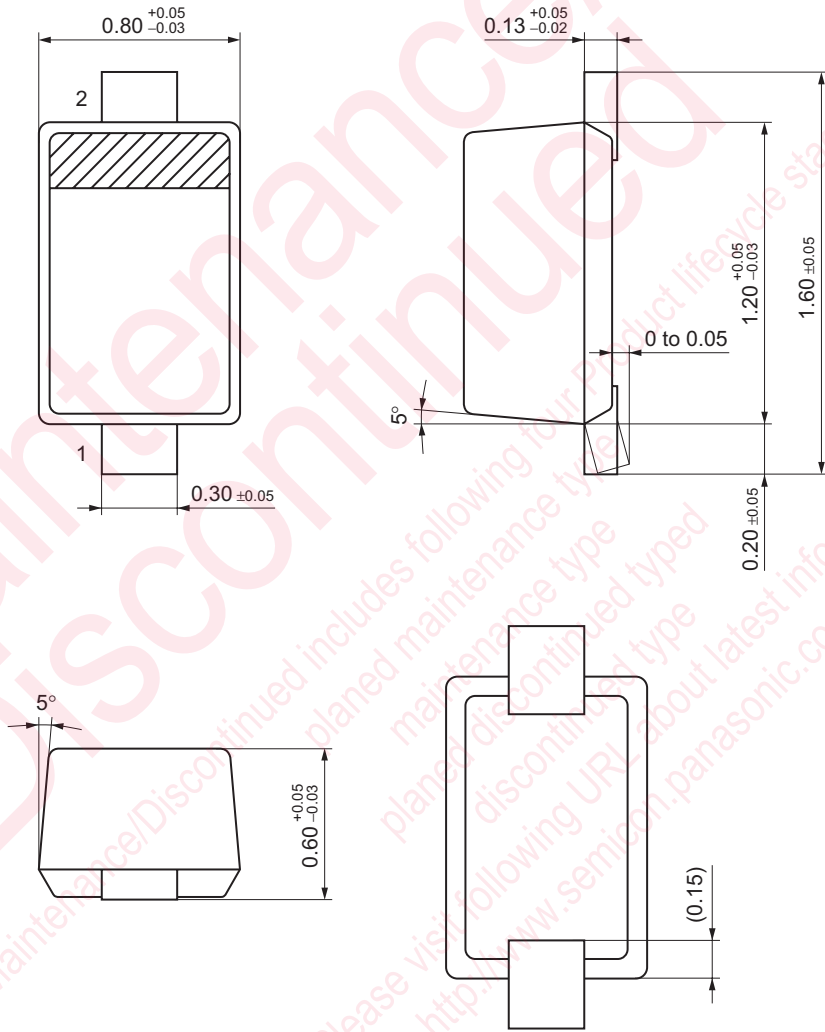
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



Maintenance/Discontinued includes following four Product lifecycle stages:
 planned maintenance type
 maintenance type
 planned discontinued type
 discontinued type
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SSMini2-F4

Unit: mm



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